

Title (en)  
MICRO-STRUCTURED SENSOR

Title (de)  
MIKROSTRUKTURIERTER SENSOR

Title (fr)  
CAPTEUR MICROSTRUCTURE

Publication  
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Application  
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Abstract (en)  
[origin: WO2005085808A1] The invention relates to a micro-structured sensor, comprising at least one measuring chip (2), wherein a first measuring area (6), comprising a first measuring structure, and a second measuring area (7) comprising a second measuring structure, is embodied, and the measuring areas (6, 7) are offset in relation to each other in a lateral direction (Y). Said micro-structured sensor also comprises a cup chip (4) which is secured, in a connecting area and in an air-tight manner, to the measuring chip (2), an intermediate chamber which is embodied between the measuring chip (2) and the cup chip (4), said intermediate chamber being sealed from the outside by the connecting area (3) and the measuring areas (6, 7) are arranged therein, and at least one contact area (20, 22), which is used to contact the measuring chip (2), is released by the cup chip (4) and is embodied on the measuring chip. The sensor can be, in particular, a gas sensor which is used to measure gas concentration or an acceleration sensor.

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